

TEK3-IMX6



- The TEK3-IMX6 is a scalable system based on an NXP i.MX6 Solo, DualLite, or Quad multicore Cortex-A9™ processor for kiosk and self-ordering applications.
- Edge-computing ready with internal mini-PCIe expansion + SIM Card slot for LTE/5G cloud connectivity.
- All aluminum ruggedized heated-dissipating fanless box PC with DIN-30 and side rail mounting.
- Orderable with single voltage 12VDC, wide voltage 9-36VDC or 802.3at PoE (power over ethernet) options and GPIO, UART, CAN interfaces (optional galvanic isolated). HDMI and VGA video support.
- Linux, Yocto, Android runtime images and full source code available.

Specifications

Sensor Information

Processor	NXP i.MX6 Solo NXP i.MX6 DualLite NXP i.MX6 Quad
Architecture	ARM Cortex-A9
PMIC	NXP MMPF0100
Memory	Up to 4GB DDR3
Storage	eMMC (4GB Default) MicroSD Card slot

Connectivity

Network LAN	1x Atheros AR8035 Gigabit LAN
Power over Ethernet	PoE function 802.3at (optional)

Expansion Interfaces

Expansion Slots	1x M.2 slot 1x mini-PCIe with SIM Card slot
-----------------	--

Power Specifications

Power Input	12V 9-36V (wide power input)
Power over Ethernet	PoE function 802.3at (optional)
Power Connector	2-pin Micro-Fit 3.0
Power Consumption	Depending on Configuration

Audio

Audio Codec	NXP SGTL5000
-------------	--------------

External Connectors

External Display	1x HDMI 1x VGA 15-pin D-SUB
Audio Connectors	1x 3.5mm jack Microphone 1x 3.5mm jack Stereo Audio in 1x 3.5mm jack Stereo Audio out
Network	1x RJ45
USB	1x USB 2.0 OTG (Type-C) 2x USB 2.0 Host
Buttons	1x Boot Select 1x Reset
Indicators	4x Programmable LED's
SIM Cardslot	1x Micro-SIM Card slot
SD Cardslot	1x MicroSD Card slot

Video

Video Decode	1080p30 + D1 (Solo/DualLite) 1080p60 H.264 (Quad)
Video Encode	1080p30 H.264 BP/Dual 720p

Operation Systems

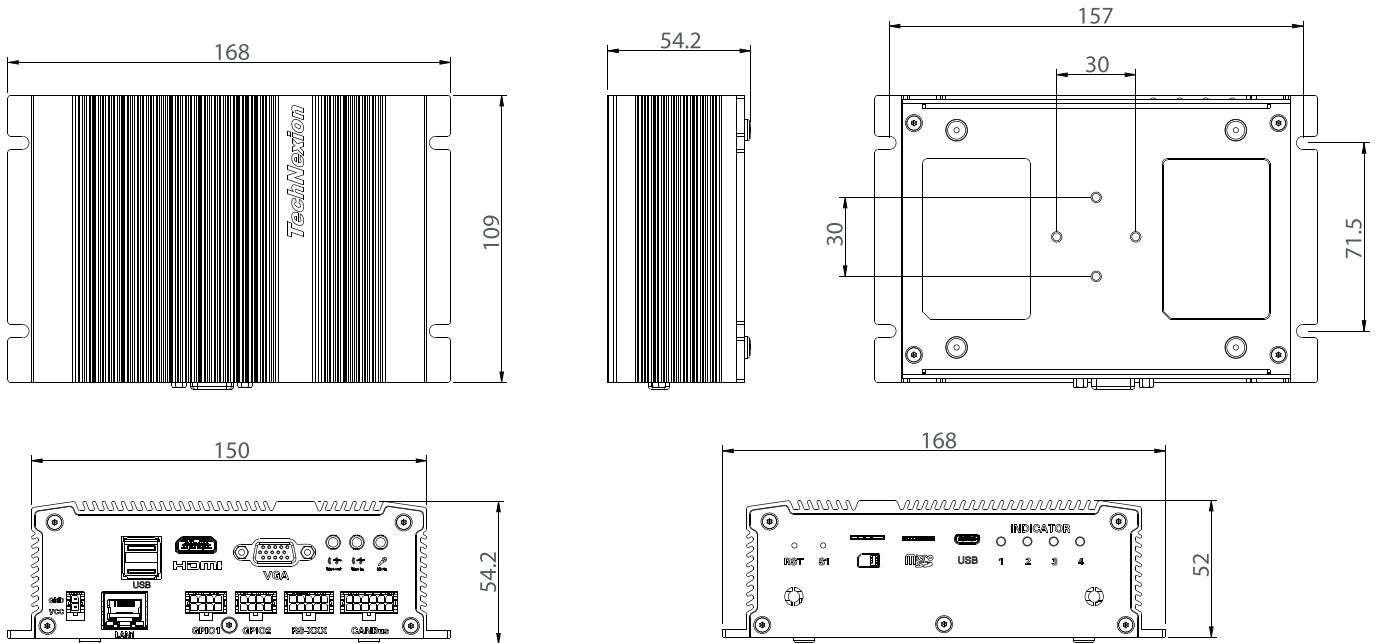
Standard Support	Linux Yocto Android
Extended Support	Commercial Linux

Sensors

RTC	Maxim integrated DS1337+ with backup Battery
-----	---



Dimensions (units in mm)



Environmental and Mechanical

Enclosure Material	Anodized Aluminium
Dimensions	168 (W) x 109 (H) x 55 (D) mm
Weight	705 grams
Temperature	Commercial: 0° to +50°C Extended: -20° to +50°C
Relative Humidity	10 to 90 %
MTBF	50 000 Hours
Shock	30G half-sine 11 ms duration
Vibration	3 Grms random 5-500Hz hr/axis
Certification	Compliant with CE / FCC / RoHS / REACH directives

Modular Expansion Options

Power Expansion Module	TXB-P1-12V-LAN1 (12V 3A) TXB-P1-1030V-LAN1 (9-36V 5A) TXB-P1-12V-POE1 (12V 3A) or (PoE 802.3at)
I/O Expansion Module	TXB-I2-GS2-GC2-GG8 (Galvanic Isolated) 2x RS-232 + 2x CAN + 8x GPIO TXB-I2-S2-C2-G8 2x RS-232 +2x CAN + 8x GPIO

Mounting Options

Surface Mounting	4 mounting holes
DIN Mounting	30mm DIN rail standard (DIN bracket separate purchase)

Order Information

TEK3-IMX6x-Rxx-Exx-Lxxx-xxxx-xxxx-xx-xxxx

	Code	Description
Processor	IMX6S	NXP i.MX6 Solo
	IMX6U	NXP i.MX6 DualLite
	IMX6Q	NXP i.MX6 Quad
Memory	R05	512MB DDR3
	R10	1GB DDR3
	R20	2GB DDR3
	R40	4GB DDR3
Storage	E04	eMMC capacity E04 = 4GB / E16 = 16GB / E32 = 32GB / E64 = 64GB
	L112	TXB-P1-12V-LAN1 (12V 3A)
	L130	TXB-P1-1030V-LAN1 (9-36V 5A)
Power Expansion	LPOE	TXB-P1-12V-POE1 (12V 3A) or (PoE 802.3at)
	-	-
	I/O Expansion	XS20
XG20		2x RS-232 + 2x CAN + 8x GPIO (Galvanic Isolated)
Temperature Range	-	Commercial Temperature range (0° to 50°C)
	TE	Extended Temperature range (-20° to +50°C)
Custom ID	XXXX	Custom Part number ID for customized Software loader and special component (BOM)